



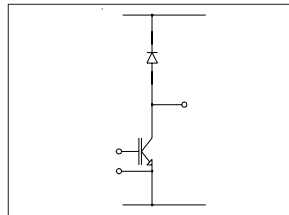
# 50MT060ULSA 50MT060ULSTA

## "LOW SIDE CHOPPER" IGBT MTP

## Ultrafast Speed IGBT

### Features

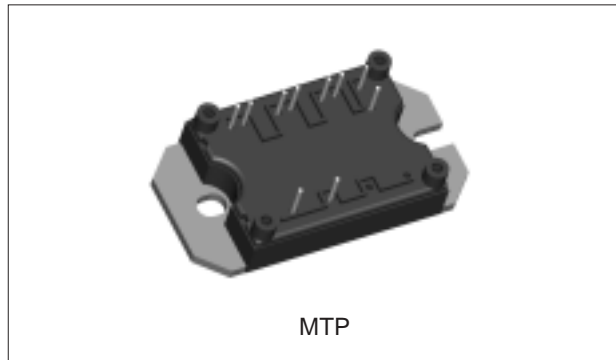
- Gen. 4 Ultrafast Speed IGBT Technology
- HEXFRED™ Diode with UltraSoft Reverse Recovery
- Very Low Conduction and Switching Losses
- Optional SMD Thermistor (NTC)
- Al<sub>2</sub>O<sub>3</sub> DBC
- Very Low Stray Inductance Design for High Speed Operation
- UL approved ( file E78996 )



$V_{CES} = 600V$   
 $I_C = 100A,$   
 $T_C = 25^\circ C$

### Benefits

- Optimized for Welding, UPS and SMPS Applications
- Operating Frequencies > 20 kHz Hard Switching, >200 kHz Resonant Mode
- Low EMI, requires Less Snubbing
- Direct Mounting to Heatsink
- PCB Solderable Terminals
- Very Low Junction-to-Case Thermal Resistance



### Absolute Maximum Ratings

Parameters		Max	Units
$V_{CES}$	Collector-to-Emitter Voltage	600	V
$I_C$	Continuos Collector Current	@ $T_C = 25^\circ C$	100
		@ $T_C = 122^\circ C$	50
$I_{CM}$	Pulsed Collector Current	200	
$I_{LM}$	Peak Switching Current	200	
$I_F$	Diode Continuous Forward Current	@ $T_C = 100^\circ C$	48
$I_{FM}$	Peak Diode Forward Current	200	
$V_{GE}$	Gate-to-Emitter Voltage	$\pm 20$	V
$V_{ISOL}$	RMS Isolation Voltage, Any Terminal to Case, t = 1 min	2500	
$P_D$	Maximum Power Dissipation	IGBT @ $T_C = 25^\circ C$	445
		@ $T_C = 100^\circ C$	175
	Diode	@ $T_C = 25^\circ C$	205
		@ $T_C = 100^\circ C$	83

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

Parameters		Min	Typ	Max	Units	Test Conditions
V <sub>(BR)CES</sub>	Collector-to-Emitter Breakdown Voltage	600			V	V <sub>GE</sub> = 0V, I <sub>C</sub> = 250μA
V <sub>CE(on)</sub>	Collector-to-Emitter Voltage		1.69	2.31		V <sub>GE</sub> = 15V, I <sub>C</sub> = 50A
			1.96	2.55		V <sub>GE</sub> = 15V, I <sub>C</sub> = 100A
			1.88	2.24		V <sub>GE</sub> = 15V, I <sub>C</sub> = 100A, T <sub>J</sub> = 150°C
V <sub>GE(th)</sub>	Gate Threshold Voltage	3		6		I <sub>C</sub> = 0.5mA
B <sub>VR</sub>	Diode Reverse Breakdown Voltage	600				I <sub>R</sub> = 200μA
ΔV <sub>GE(th)</sub> /ΔT <sub>J</sub>	Temperature Coeff. of Threshold Voltage		- 13		mV/°C	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 500μA
g <sub>fe</sub>	Forward Transconductance	22	29		S	V <sub>CE</sub> = 50V, I <sub>C</sub> = 100A
I <sub>CES</sub>	Collector-to-Emitter Leaking Current			0.25	mA	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V
				6		V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V, T <sub>J</sub> = 150°C
V <sub>FM</sub>	Diode Forward Voltage Drop		1.64	1.82	V	I <sub>F</sub> = 100A, V <sub>GE</sub> = 0V
			1.56	1.74		I <sub>F</sub> = 100A, V <sub>GE</sub> = 0V, T <sub>J</sub> = 150°C
I <sub>GES</sub>	Gate-to-Emitter Leakage Current			± 250	nA	V <sub>GE</sub> = ± 20V

**Switching Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

Parameters		Min	Typ	Max	Units	Test Conditions
Q <sub>g</sub>	Total Gate Charge (turn-on)		370	555	nC	I <sub>C</sub> = 100A
Q <sub>ge</sub>	Gate-Emitter Charge (turn-on)		64	96		V <sub>CC</sub> = 480V
Q <sub>gc</sub>	Gate-Collector Charge (turn-on)		163	245		V <sub>GE</sub> = 15V
E <sub>on</sub>	Turn-On Switching Loss		0.7	1.2	mJ	I <sub>C</sub> = 50A, V <sub>CC</sub> = 480V, V <sub>GE</sub> = 15V, R <sub>g</sub> = 5Ω
E <sub>off</sub>	Turn-Off Switching Loss		1.7	2.6		
E <sub>ts</sub>	Total Switching Loss		2.4	3.8		Energy losses include tail and diode reverse recovery
E <sub>on</sub>	Turn-On Switching Loss		1.1	1.7	mJ	I <sub>C</sub> = 50A, V <sub>CC</sub> = 480V, V <sub>GE</sub> = 15V
E <sub>off</sub>	Turn-Off Switching Loss		2.5	3.8		R <sub>g</sub> = 5Ω, T <sub>J</sub> = 125°C
E <sub>ts</sub>	Total Switching Loss		3.6	5.5		Energy losses include tail and diode reverse recovery
C <sub>ies</sub>	Input Capacitance		9800	14700		V <sub>GE</sub> = 0V
C <sub>oes</sub>	Output Capacitance		602	903	pF	V <sub>CC</sub> = 30V
C <sub>res</sub>	Reverse Transfer Capacitance		121	182		f = 1.0 MHz
C <sub>t</sub>	Diode Junction Capacitance		118	177		V <sub>r</sub> = 600V, f = 1.0 MHz
t <sub>rr</sub>	Diode Reverse Recovery Time		99	150	ns	V <sub>CC</sub> = 480V, I <sub>C</sub> = 50A
I <sub>rr</sub>	Diode Peak Reverse Current		6.5	9.8	A	di/dt = 200A/μs
Q <sub>rr</sub>	Diode Recovery Charge		320	735	nC	R <sub>g</sub> = 5Ω
di <sub>(rec)</sub> /dt	Diode PeakRate of Fall of Recovery During t <sub>b</sub>		236		A/μs	

**Thermistor Specifications (50MT060ULSTA only)**

Parameters	Min	Typ	Max	Units	Test Conditions
R <sub>0</sub> <sup>(1)</sup> Resistance		30		kΩ	T <sub>0</sub> = 25°C
β <sup>(1)(2)</sup> Sensitivity index of the thermistor material		4000		K	T <sub>0</sub> = 25°C T <sub>1</sub> = 85°C

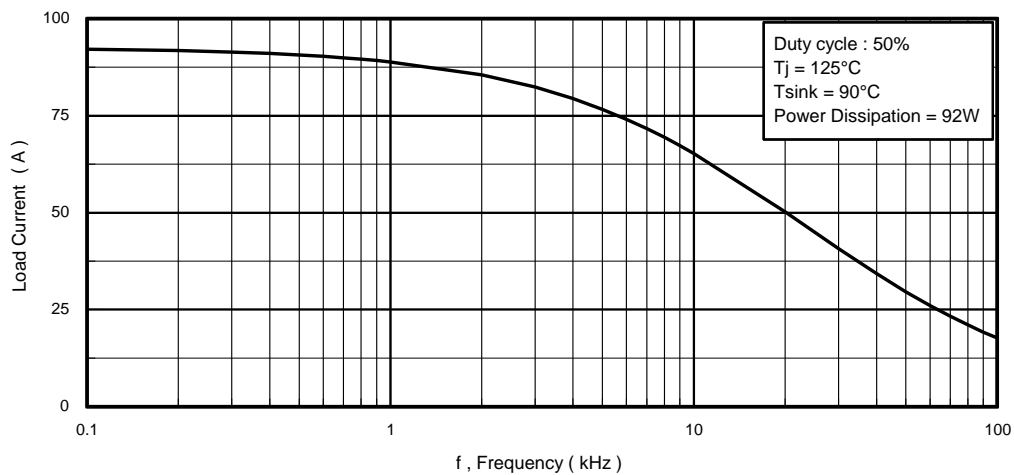
(1) T<sub>0</sub>, T<sub>1</sub> are thermistor's temperatures

$$(2) \frac{R_0}{R_1} = \exp \left[ \beta \left( \frac{1}{T_0} - \frac{1}{T_1} \right) \right]. \text{ Temperatures in kelvin}$$

**Thermal- Mechanical Specifications**

Parameters	Min	Typ	Max	Units
T <sub>J</sub> Operating Junction Temperature Range	- 40		150	°C
T <sub>STG</sub> Storage Temperature Range	- 40		125	
R <sub>thJC</sub> Junction-to-Case	IGBT		0.28	°C/ W
	Diode		0.6	
R <sub>thCS</sub> Case-to-Sink (Heatsink Compound Thermal Conductivity = 1 W/mK)	Module	0.06		
T Mounting torque to heatsink	(3)	3 ± 10%		Nm
Wt Weight		66		g

(3) A mounting compound is recommended and the torque should be checked after 3 hours to allow for the spread of the compound. Lubricated threads



**Fig. 1 - Typical Load Current vs. Frequency**  
(Load Current = I<sub>RMS</sub> of fundamental)

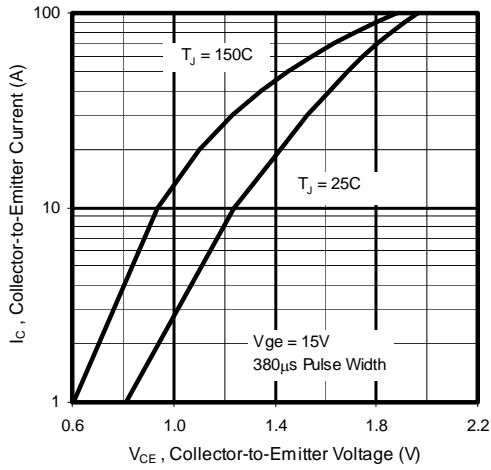


Fig. 2 - Typical Output Characteristics

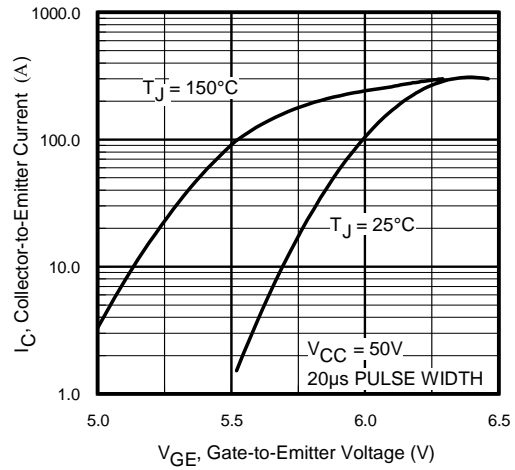


Fig. 3 - Typical Transfer Characteristics

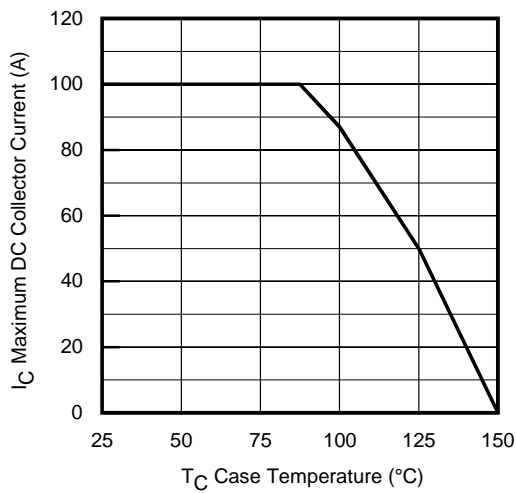


Fig. 4 - Maximum Collector Current vs. Case Temperature

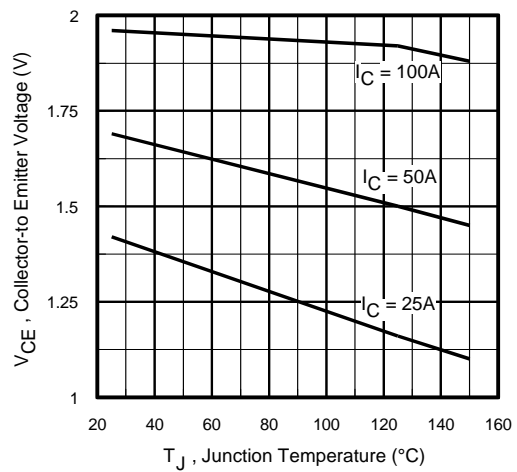


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

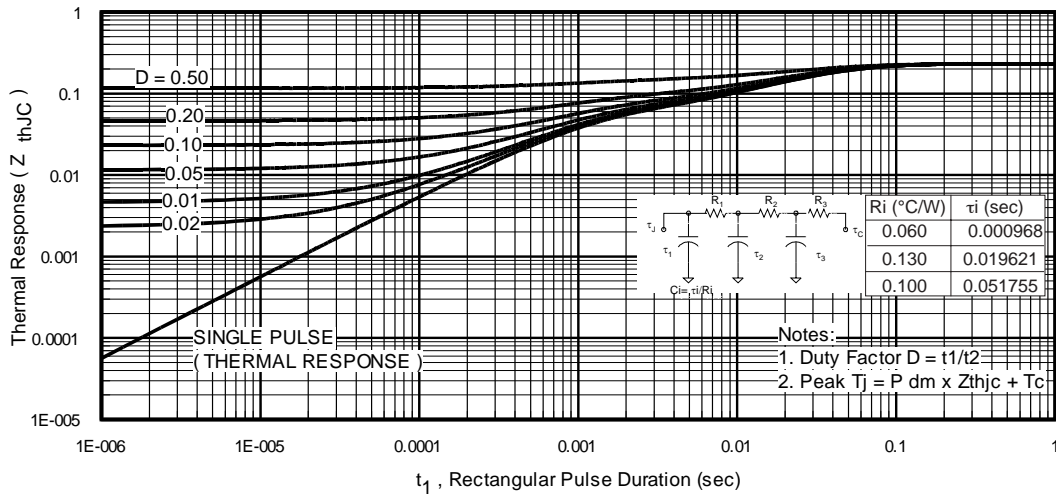


Fig. 6a Maximum Transient Thermal Impedance, Junction-to-Case (IGBT)

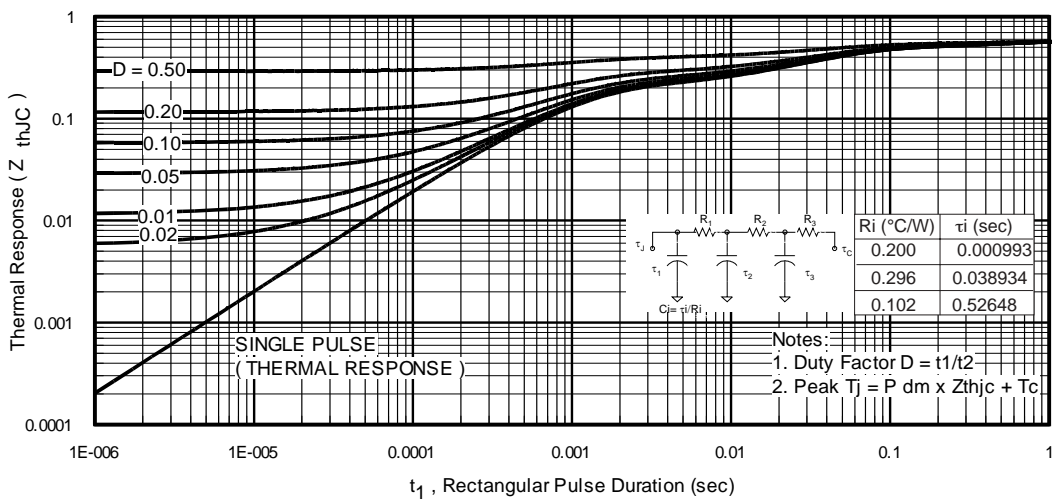


Fig. 6b Maximum Transient Thermal Impedance, Junction-to-Case (DIODE)

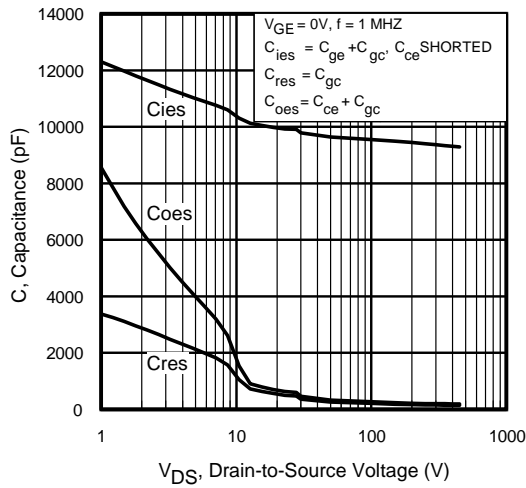


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

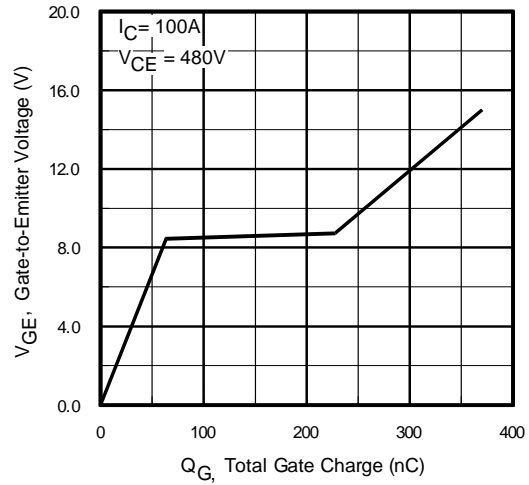


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

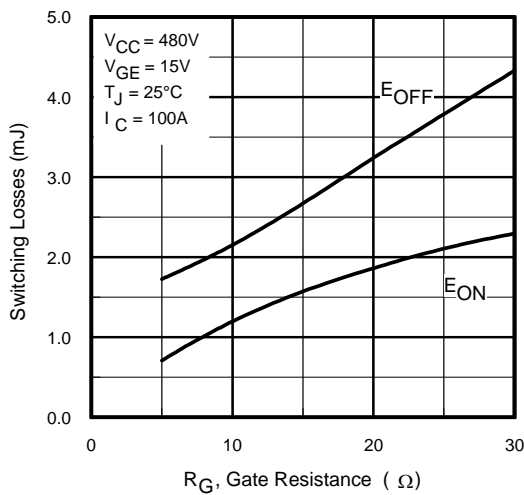


Fig. 9 - Typical Switching Losses vs. Gate Resistance

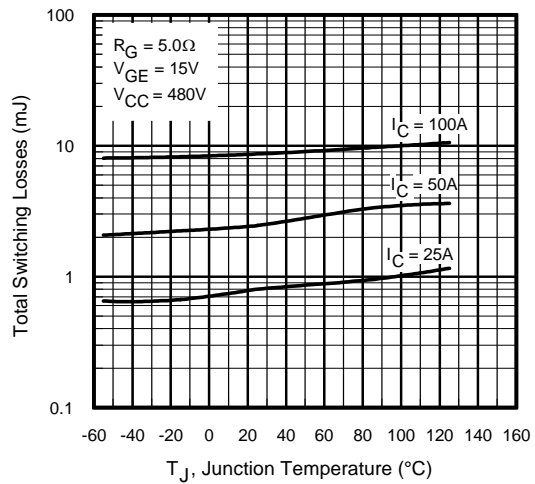


Fig. 10 - Typical Switching Losses vs. Junction Temperature

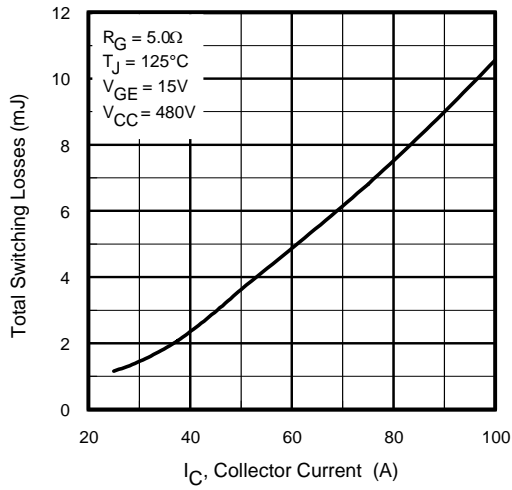


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

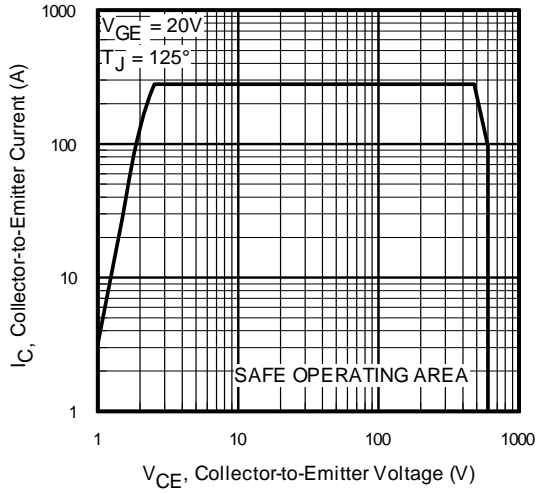


Fig. 12 - Turn-Off SOA

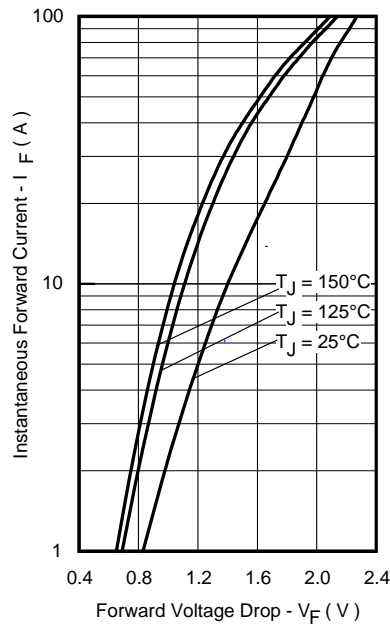


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

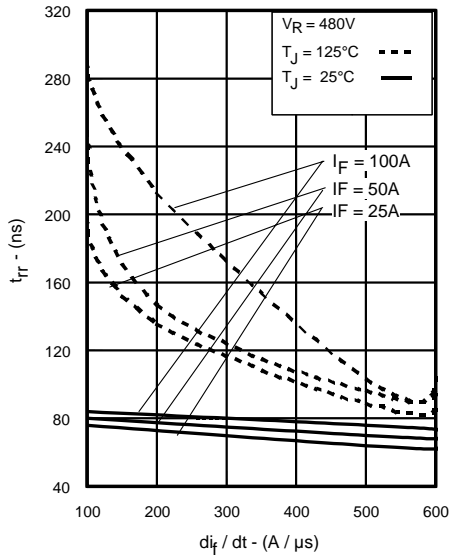


Fig. 14 - Typical Reverse Recovery vs.  $di_f/dt$

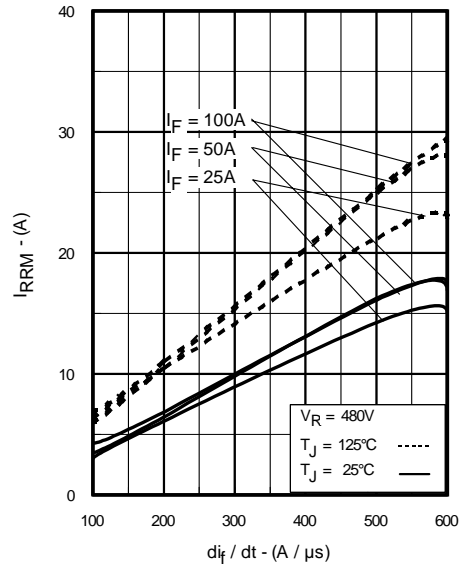


Fig. 15 - Typical Recovery Current vs.  $di_f/dt$

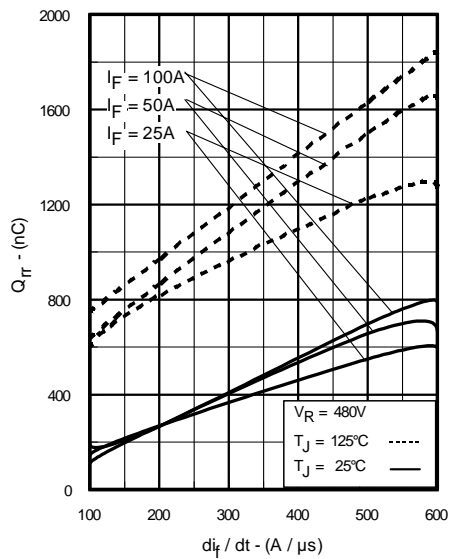


Fig. 16 - Typical Stored Charge vs.  $di_f/dt$

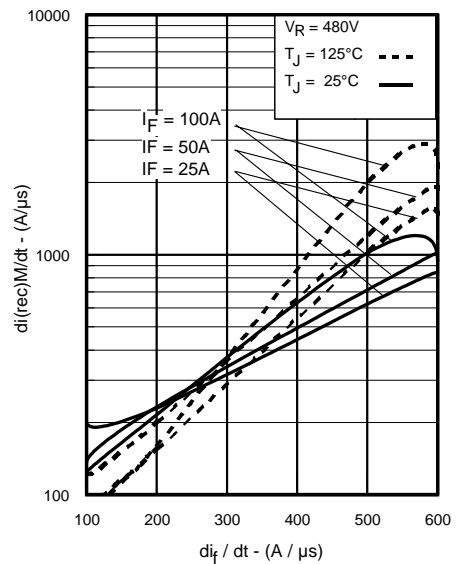
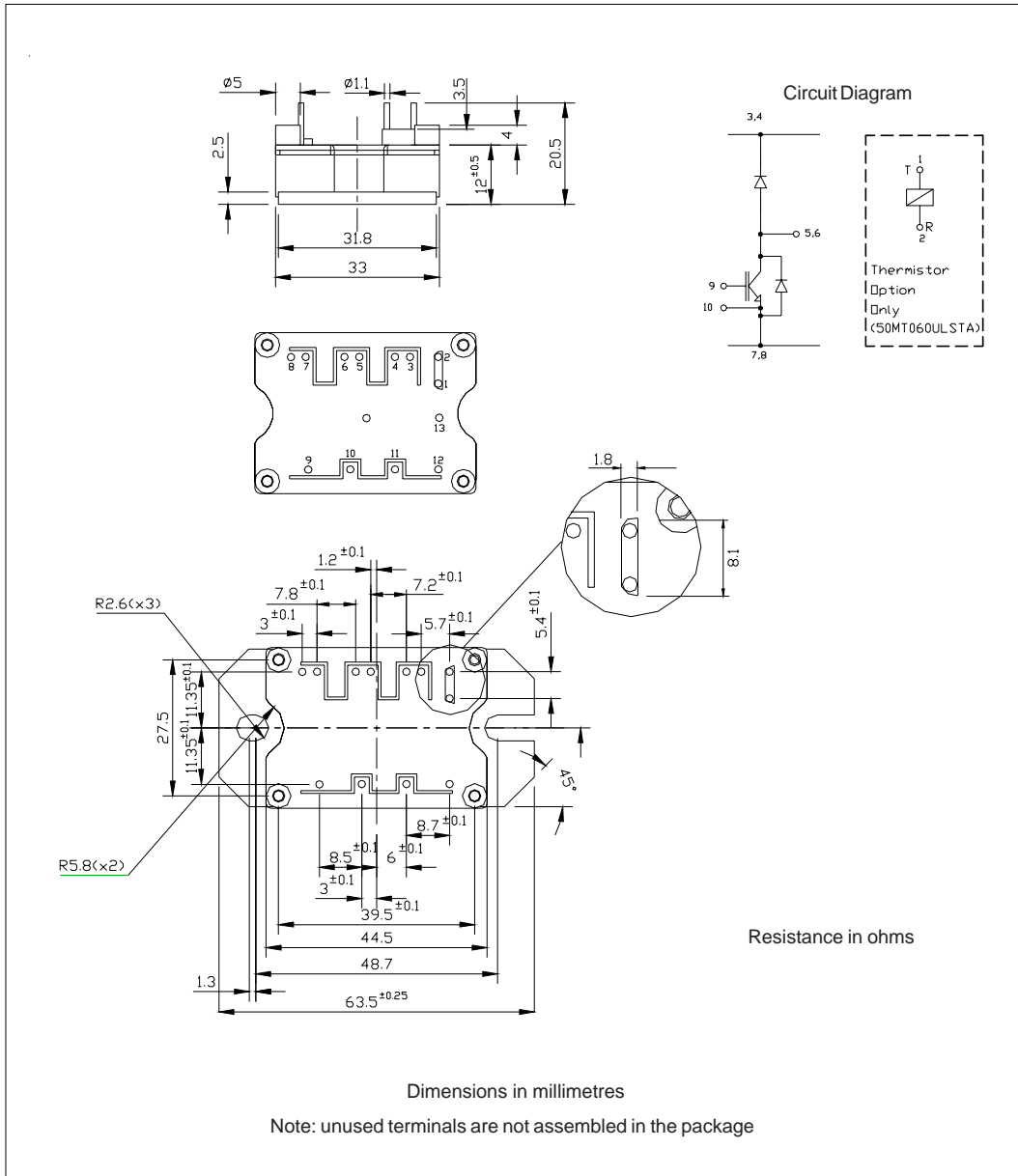


Fig. 17 - Typical  $di_{(rec)M}/dt$  vs.  $di_f/dt$



**Outline Table**



### Ordering Information Table

Device Code	
50	MT
060	U
LS	T
A	
①	②
③	④
⑤	⑥
⑦	

<p><b>1</b></p> <p><b>2</b></p> <p><b>3</b></p> <p><b>4</b></p> <p><b>5</b></p> <p><b>6</b></p> <p><b>7</b></p>	<p>- Current Rating (50 = 50A)</p> <p>- Essential Part Number</p> <p>- Voltage rating (060 = 600V)</p> <p>- Speed/Type (U = Ultra Fast IGBT)</p> <p>- Circuit Configuration (LS = Low Side Chopper)</p> <p>- Special Option</p> <ul style="list-style-type: none"> <li>• none = no special option</li> <li>• T = Thermistor</li> </ul> <p>- A = Al<sub>2</sub>O<sub>3</sub> DBC Substrate</p>
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Data and specifications subject to change without notice.  
This product has been designed and qualified for Industrial Level.  
Qualification Standards can be found on IR's Web site.